



# 1Mx32 SRAM MODULE

## FEATURES

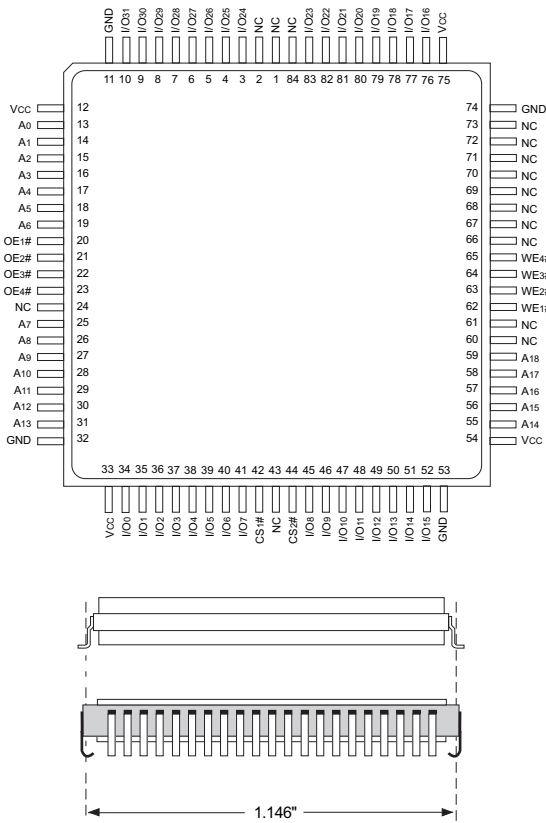
- Access Time of 70, 85, 100, 120ns
- 84 lead, 28mm CQFP, (Package 511)
- Organized as two banks of 512Kx32, User Configurable as 1Mx16 or 2Mx8
- Commercial, Industrial and Military Temperature Ranges
- TTL Compatible Inputs and Outputs

- 5V Power Supply
- Low Power CMOS
- Weight - WS1M32-XG3X - 20 grams typical

\*This product is under development, is not qualified or characterized and is subject to change without notice.

## PIN CONFIGURATION FOR WS1M32-XG3X

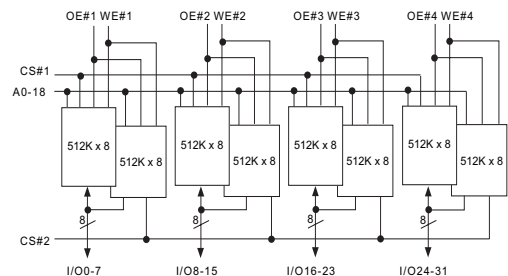
### TOP VIEW



### PIN DESCRIPTION

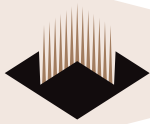
I/O0-31	Data Inputs/Outputs
A0-18	Address Inputs
WE1-4#	Write Enables
CS1-2#	Chip Selects
OE1-4#	Output Enables
Vcc	Power Supply
GND	Ground
NC	Not Connected

### BLOCK DIAGRAM



Note: CS#1 & CS#2 are used as bank select

The WEDC 84 lead G3 CQFP fills the same fit and function as the JEDEC 84 lead CQFJ or 84 PLCC. But the G3 has the TCE and lead inspection advantage of the CQFP form.



## ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T <sub>A</sub>	-40	+85	°C
Storage Temperature	T <sub>STG</sub>	-65	+150	°C
Signal Voltage Relative to GND	V <sub>G</sub>	-0.5	V <sub>CC</sub> +0.5	V
Junction Temperature	T <sub>J</sub>		150	°C
Supply Voltage	V <sub>CC</sub>	-0.5	4.6	V

## CAPACITANCE

T<sub>A</sub> = +25°C

Parameter	Symbol	Conditions	Max	Unit
OE#1-4 capacitance	C <sub>OE</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	30	pF
WE#1-4 capacitance	C <sub>WE</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	30	pF
CS#1-2 capacitance	C <sub>CS</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	30	pF
Data I/O capacitance	C <sub>I/O</sub>	V <sub>I/O</sub> = 0V, f = 1.0MHz	30	pF
Address input capacitance	C <sub>AD</sub>	V <sub>IN</sub> = 0V, f = 1.0MHz	100	pF

This parameter is guaranteed by design, but not tested.

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V <sub>CC</sub>	3.0	3.6	V
Input High Voltage	V <sub>IH</sub>	2.2	V <sub>CC</sub> + 0.3	V
Input Low Voltage	V <sub>IL</sub>	-0.3	+0.8	V
Operating Temperature (Ind.)	T <sub>A</sub>	-40	+85	°C

## TRUTH TABLE

CS1#	CS2#	OE#	WE#	Mode	Data I/O	Power
H	H	X	X	Standby	High Z	Standby
L	H	L	H	Read	Data Out	Active
L	H	H	H	Out Disable	High Z	Active
L	H	X	L	Write	Data In	Active
H	L	L	H	Read	Data Out	Active
H	L	H	H	Out Disable	High Z	Active
H	L	X	L	Write	Data In	Active
L	L	X	X	Invalid State	Invalid State	Invalid State

## DC CHARACTERISTICS

V<sub>CC</sub> = 3.3V ± 0.3V, -55°C ≤ T<sub>A</sub> ≤ +125°C

Parameter	Symbol	Conditions	Min	Max	Units
Input Leakage Current	I <sub>LI</sub>	V <sub>CC</sub> = 5.5, V <sub>IN</sub> = GND to V <sub>CC</sub>		10	μA
Output Leakage Current	I <sub>LO</sub>	CS# = V <sub>IH</sub> , OE# = V <sub>IH</sub> , V <sub>OUT</sub> = GND to V <sub>CC</sub>		10	μA
Operating Supply Current x 32 Mode	I <sub>CC</sub> x 32	CS# = V <sub>IL</sub> , OE# = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		220	mA
Standby Current	I <sub>SB</sub>	CS# = V <sub>IH</sub> , OE# = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		10	mA
Standby Current (Low Power)	I <sub>SB2</sub>	CS# = V <sub>IH</sub> , OE# = V <sub>IH</sub> , f = 5MHz, V <sub>CC</sub> = 5.5		900	μA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 8mA, V <sub>CC</sub> = 4.5		0.4	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -4.0mA, V <sub>CC</sub> = 4.5	2.4		V

NOTE: DC test conditions: V<sub>IH</sub> = V<sub>CC</sub> - 0.3V, V<sub>IL</sub> = 0.3V



## AC CHARACTERISTICS

V<sub>CC</sub> = 5.0V, GND = 0V, -55°C ≤ T<sub>A</sub> ≤ +125°C

Parameter	Symbol	-70		-85		-100		-120		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle										
Read Cycle Time	t <sub>RC</sub>	70		85		100		120		ns
Address Access Time	t <sub>AA</sub>		70		85		100		120	ns
Output Hold from Address Change	t <sub>OH</sub>	5		5		5		5		ns
Chip Select Access Time	t <sub>ACS</sub>		70		85		100		120	ns
Output Enable to Output Valid	t <sub>OE</sub>		35		40		50		60	ns
Chip Select to Output in Low Z	t <sub>CLZ</sub> <sup>1</sup>	10		10		10		10		ns
Output Enable to Output in Low Z	t <sub>OLZ</sub> <sup>1</sup>	5		5		5		5		ns
Chip Disable to Output in High Z	t <sub>CHZ</sub> <sup>1</sup>		25		25		35		35	ns
Output Disable to Output in High Z	t <sub>OHZ</sub> <sup>1</sup>		25		25		35		35	ns

1. This parameter is guaranteed by design but not tested.

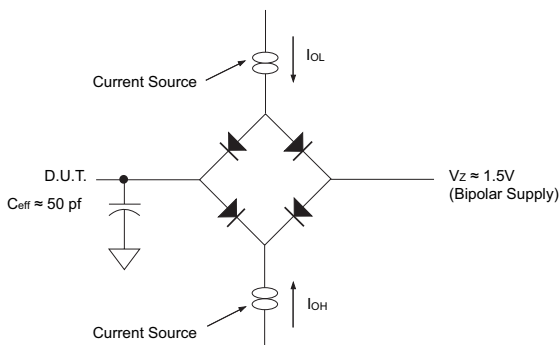
## AC CHARACTERISTICS

V<sub>CC</sub> = 5.0V, GND = 0V, -55°C ≤ T<sub>A</sub> ≤ +125°C

Parameter	Symbol	-70		-85		-100		-120		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle										
Write Cycle Time	t <sub>WC</sub>	70		85		100		120		ns
Chip Select to End of Write	t <sub>CW</sub>	60		75		80		100		ns
Address Valid to End of Write	t <sub>AW</sub>	60		75		80		100		ns
Data Valid to End of Write	t <sub>DW</sub>	30		30		40		40		ns
Write Pulse Width	t <sub>WP</sub>	50		50		60		60		ns
Address Setup Time	t <sub>AS</sub>	0		0		0		0		ns
Address Hold Time	t <sub>AH</sub>	5		5		5		5		ns
Output Active from End of Write	t <sub>OW</sub> <sup>1</sup>	5		5		5		5		ns
Write Enable to Output in High Z	t <sub>WHZ</sub> <sup>1</sup>		25		25		35		35	ns
Data Hold Time	t <sub>DH</sub>	0		0		0		0		ns

1. This parameter is guaranteed by design but not tested.

### AC TEST CIRCUIT



### AC TEST CONDITIONS

Parameter	Typ	Unit
Input Pulse Levels	V <sub>IL</sub> = 0, V <sub>IH</sub> = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

#### NOTES:

V<sub>Z</sub> is programmable from -2V to +7V.

I<sub>OL</sub> & I<sub>OH</sub> programmable from 0 to 16mA.

Tester Impedance Z<sub>0</sub> = 75Ω.

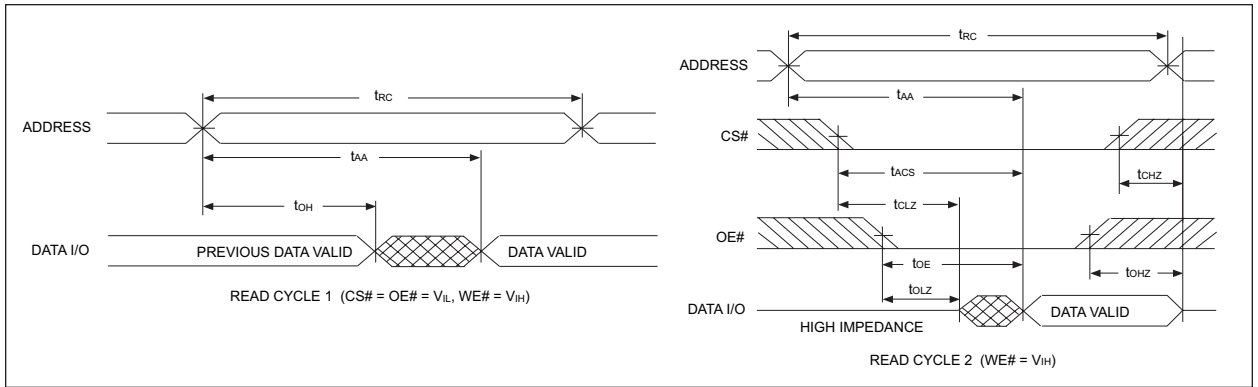
V<sub>Z</sub> is typically the midpoint of V<sub>OH</sub> and V<sub>OL</sub>.

I<sub>OL</sub> & I<sub>OH</sub> are adjusted to simulate a typical resistive load circuit.

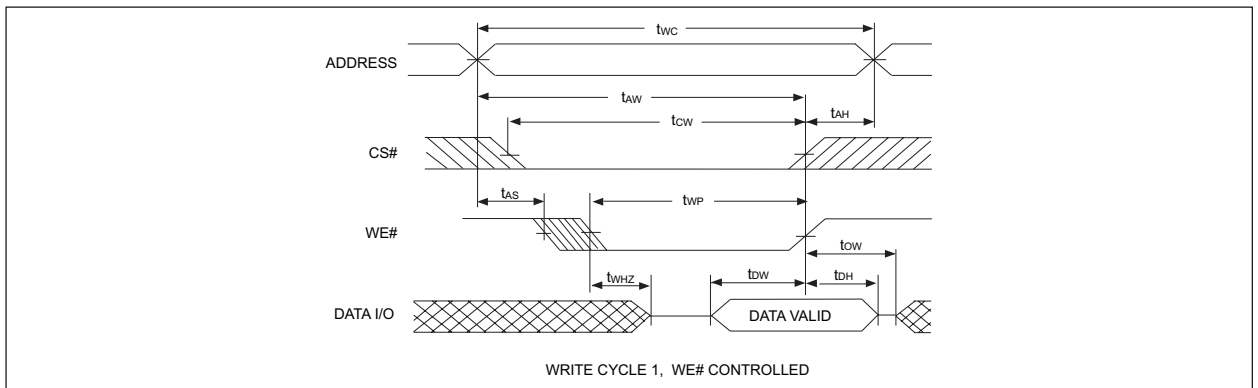
ATE tester includes jig capacitance.



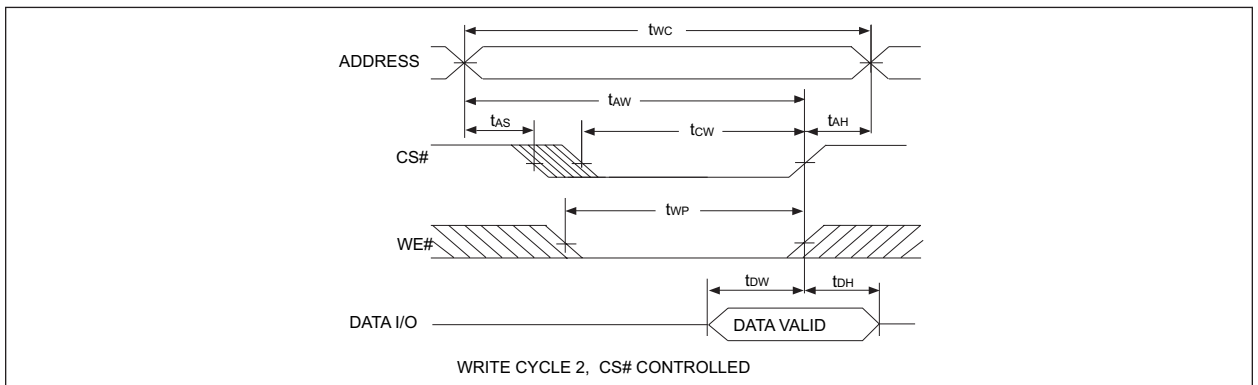
**TIMING WAVEFORM - READ CYCLE**



**WRITE CYCLE - WE# CONTROLLED**

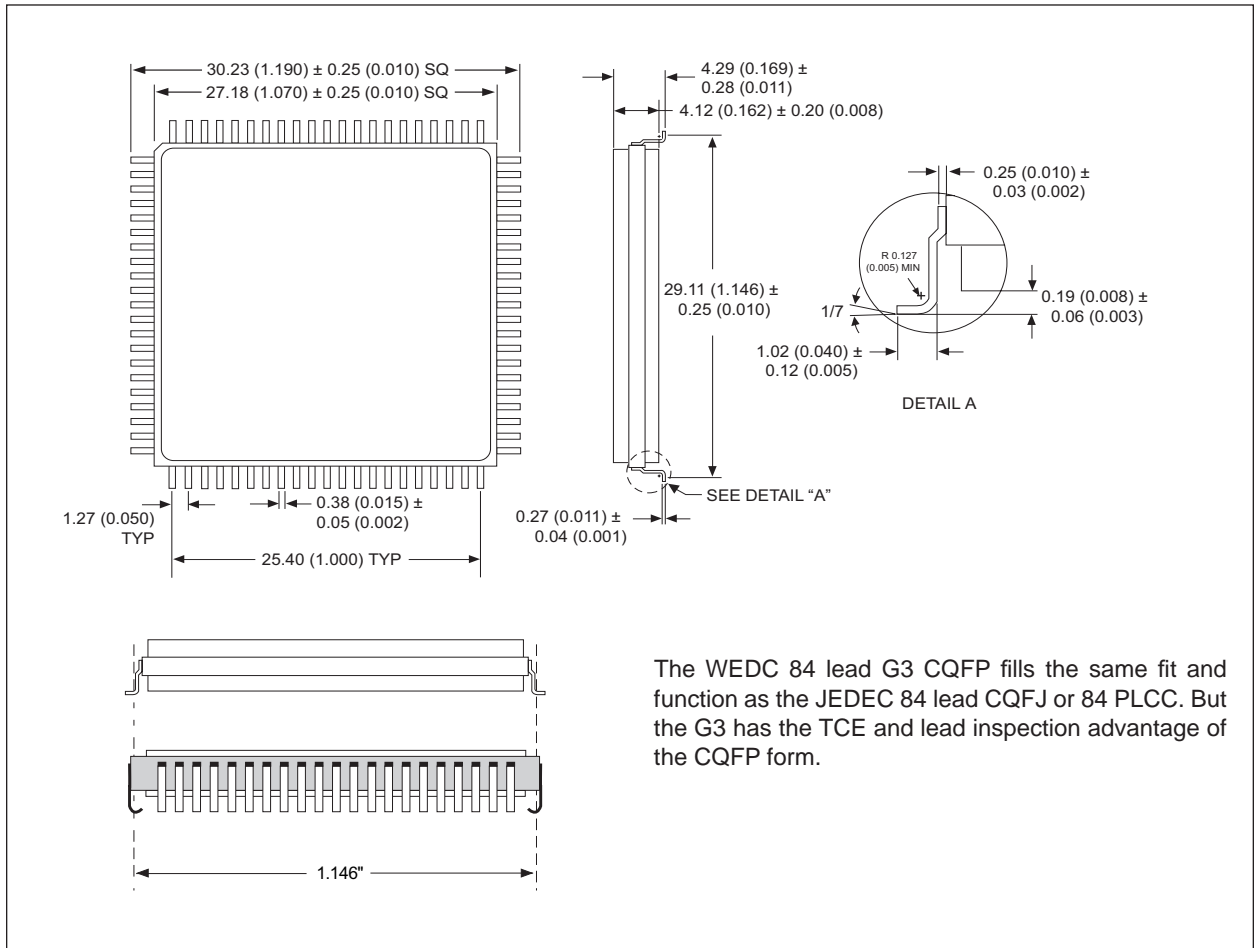


**WRITE CYCLE - CS# CONTROLLED**





**PACKAGE 511: 84 LEAD, CERAMIC QUAD FLAT PACK (G3)**



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ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



### ORDERING INFORMATION

**W S 1M32 - XX G3 X X**

**LEAD FINISH:**

Blank = Gold plated leads

A = Solder dip leads

**DEVICE GRADE:**

M = Military -55°C to +125°C

C = Commercial -40°C to +85°C

I = Industrial 0° to +70°C

**PACKAGE TYPE:**

G3 = 28 mm CQFP (Package 511)

**ACCESS TIME (ns)**

**ORGANIZATION, two banks of 512Kx32**

User configurable as 2Mx16 or 4Mx8

**SRAM**

**WHITE ELECTRONIC DESIGNS CORP.**